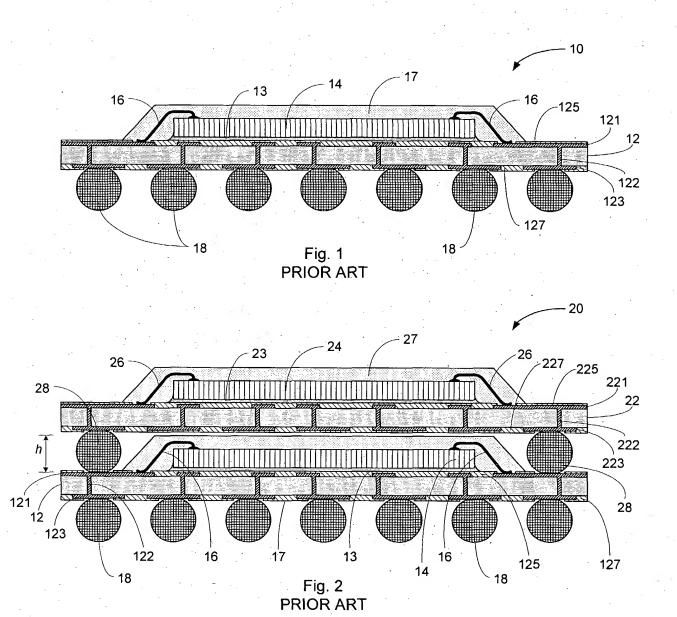
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
Having Package Stacked Over...
Attorney Docket: CPAC 1017-6 D4
Sheet 1 of 7

177



Inventor: Marcos Kamezos
Title: Semiconductor Multi-Package Module
Having Package Stacked Over...
Attorney Docket: CPAC 1017-6 D4
Sheet 2 of 7

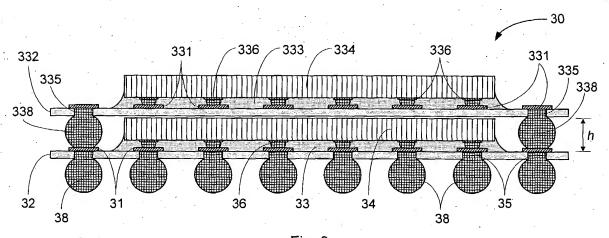


Fig. 3 PRIOR ART

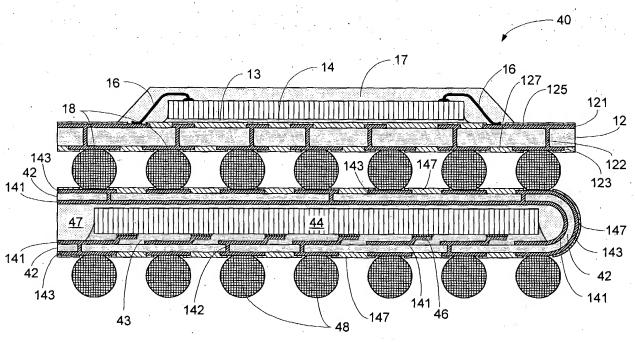
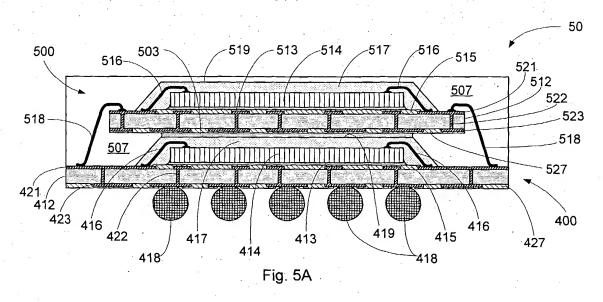
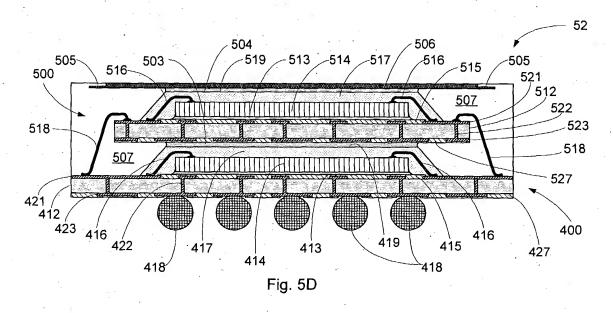
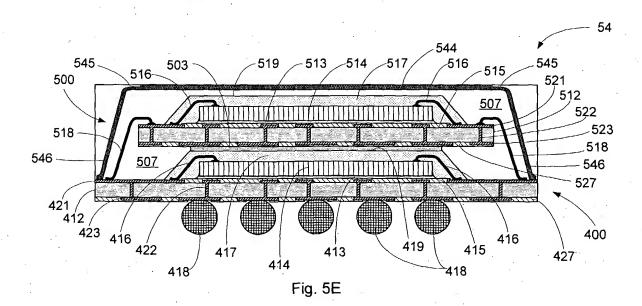


Fig. 4 PRIOR ART

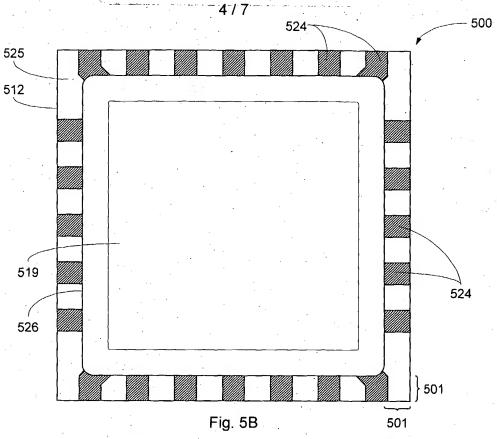
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
Having Package Stacked Over...
Attorney Docket: CPAC 1017-6 D4
Sheet 3 of 7







Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
Having Package Stacked Over...
Attorney Docket: CPAC 1017-6 D4
Sheet 4 of 7



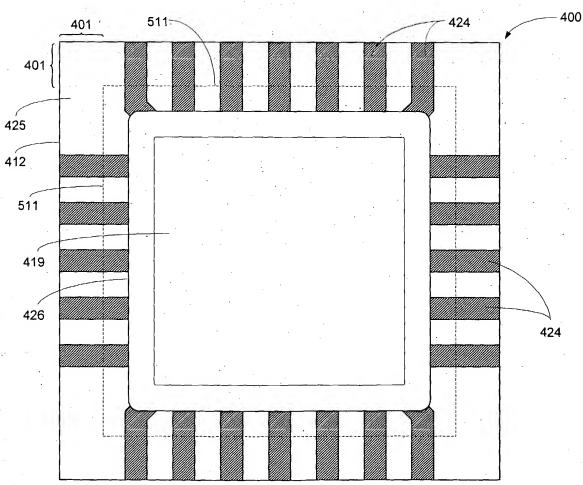
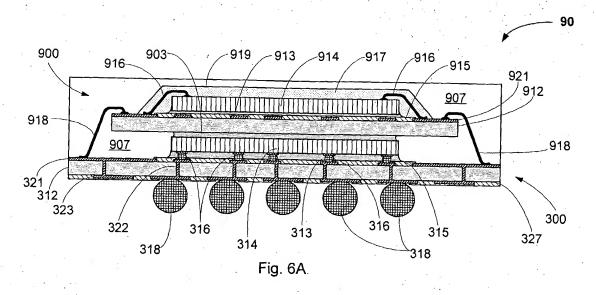
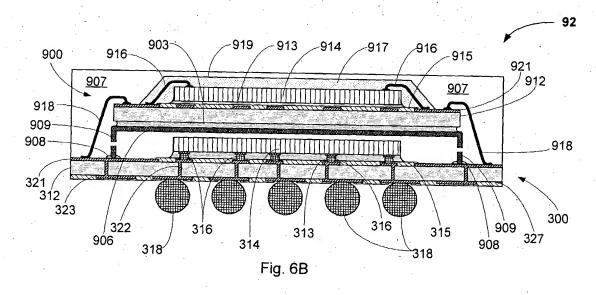
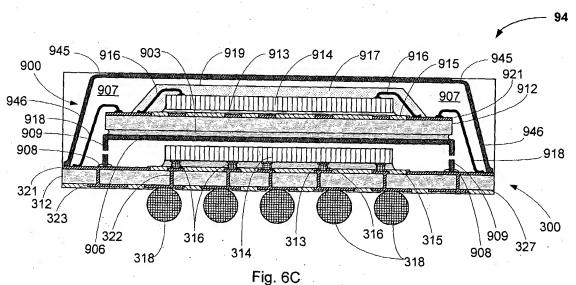


Fig. 5C

Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
Having Package Stacked Over...
Attorney Docket: CPAC 1017-6 D4
Sheet 5 of 7







Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
Having Package Stacked Over...
Attorney Docket: CPAC 1017-6 D4
Sheet 6 of 7

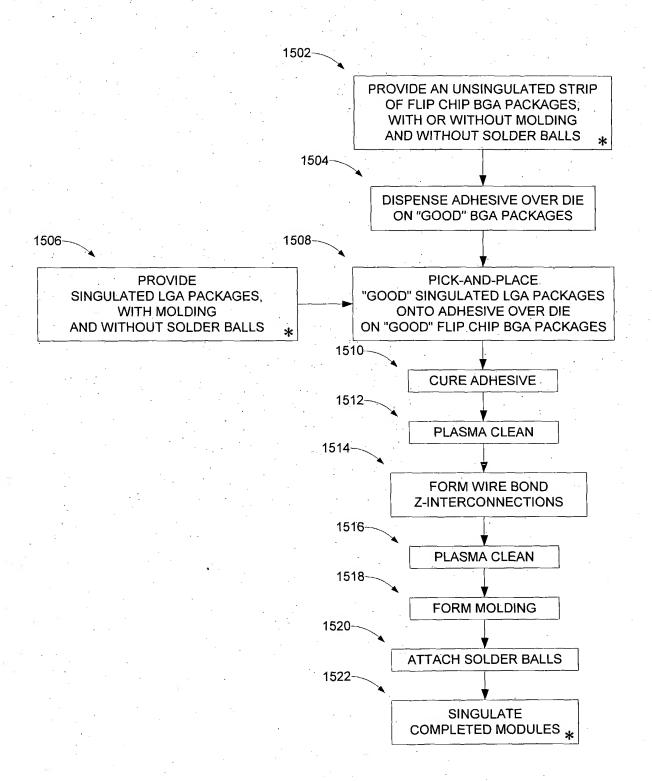


Fig. 7

Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
Having Package Stacked Over...
Attorney Docket: CPAC 1017-6 D4
Sheet 7 of 7

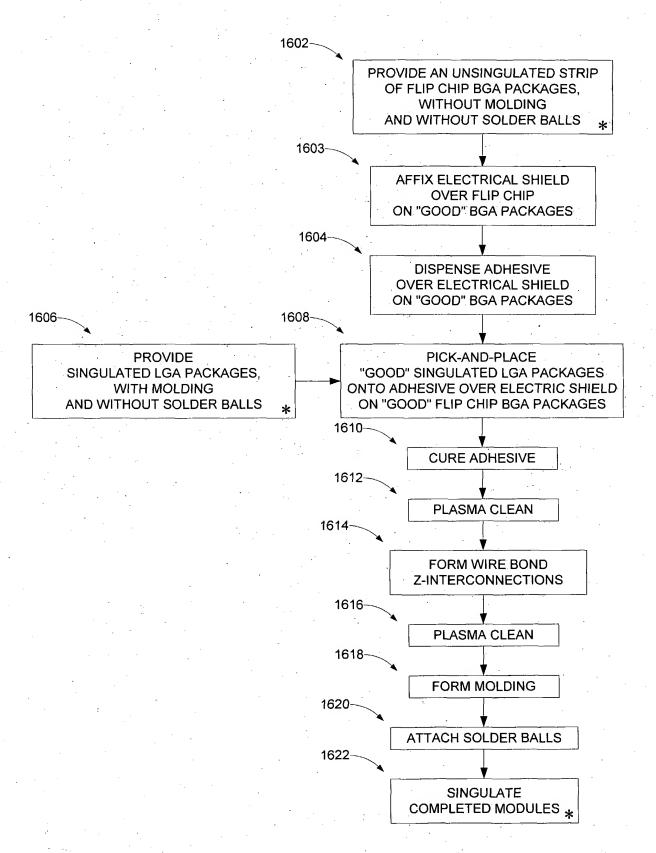


Fig. 8